

Serial No. 10/090,151  
December 22, 2003  
Reply to the Office Action dated September 24, 2003  
Page 2 of 7

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (canceled).

Claim 2 (currently amended): The surface acoustic wave device according to claim 49, wherein the metal bump connections comprise one of elemental gold and an alloy including gold as the primary component.

Claim 3 (currently amended): The surface acoustic wave device according to claim 49, wherein the metal bump connections include a metal bump disposed between each of the electrode pads and the corresponding electrode pattern section on the electronic component package.

Claim 4 (previously presented): The method for making the surface acoustic wave device according to claim 3, wherein the metal bump includes a semispherical main portion and a substantially perpendicular projection.

Claim 5 (currently amended): A communication apparatus comprising the surface acoustic wave device according to claim 49.

Claim 6 (currently amended): The surface acoustic wave device according to claim 49, wherein the copper content is in the range of about 3.5 to about 25 percent by weight.

Serial No. 10/090,151  
December 22, 2003  
Reply to the Office Action dated September 24, 2003  
Page 3 of 7

Claim 7 (currently amended): The surface acoustic wave device according to claim 49, wherein the electrode pads include aluminum and copper, the copper content being in the range of about 3.5 to about 25 percent by weight.

Claim 8 (currently amended): The surface acoustic wave device according to claim 49, wherein the copper content is in the range of about 3.5 to about 18 percent by weight.

Claim 9 (currently amended): ~~The surface acoustic wave device according to claim 1, further comprising:~~ A surface acoustic wave device comprising:

a surface acoustic wave element including a piezoelectric substrate having interdigital electrodes and electrode pads thereon, the electrode pads being arranged to input and output electrical signals to and from the respective interdigital electrodes;

an electronic component package supporting the surface acoustic wave element, the electronic component package including electrode pattern sections arranged to input and output electrical signals;

metal bump connections electrically connecting the electrode pads to the respective electrode pattern sections; and

intermediate electrodes and upper electrodes on the respective electrode pads; wherein

the electrode pads include aluminum as a major component and copper as a minor component, the copper content being at least about 3.5 percent by weight; and

the intermediate electrodes are disposed between the respective electrode pads and the respective upper electrodes and include a material for enhancing the bonding strength therebetween, and the upper electrodes include a material for enhancing the bonding strength between the respective intermediate electrodes and the respective metal bump connections.

Serial No. 10/090,151  
December 22, 2003  
Reply to the Office Action dated September 24, 2003  
Page 4 of 7

Claim 10 (currently amended): The surface acoustic wave device according to claim 49, wherein the electronic component package includes a bottom plate, a sidewall component, a cover and a cavity, the cavity accommodates the surface acoustic wave element therein and is surrounded by the bottom plate, the sidewall component and the cover.

Claim 11 (original): The surface acoustic wave device according to claim 10, wherein the electrode pattern sections are provided on an inner surface of the bottom plate.

Claim 12 (original): The surface acoustic wave device according to claim 10, wherein a plurality of external connection terminals is provided on an outer surface of the bottom plate of the electronic component package, and each of the plurality of external connection terminals are electrically connected to respective electrode pattern sections.

Claim 13 (original): The surface acoustic wave device according to claim 10, wherein the surface acoustic wave element is mounted face down in the electronic component package such that the interdigital electrodes face the bottom plate of electronic component package.

Claim 14 (original): The surface acoustic wave device according to claim 10, wherein the surface acoustic wave element is spaced from the bottom plate of the electronic component by a gap.

Claim 15 (original): The surface acoustic wave device according to claim 9, wherein the intermediate electrodes are made of NiCr.

Serial No. 10/090,151  
December 22, 2003  
Reply to the Office Action dated September 24, 2003  
Page 5 of 7

Claim 16 (original): The surface acoustic wave device according to claim 9, wherein the upper electrodes are made of one of elemental aluminum and an aluminum alloy.

Claim 17 (currently amended): The surface acoustic wave device according to claim 49, wherein the electrode pattern sections are plated with gold.

Claims 18-22 (canceled).

Claim 23 (new): The surface acoustic wave device according to claim 15, wherein the copper content is in the range of about 3.5 to about 25 percent by weight.

Claim 24 (new): The surface acoustic wave device according to claim 15, wherein the electrode pads include aluminum and copper, the copper content being in the range of about 3.5 to about 25 percent by weight.

Claim 25 (new): The surface acoustic wave device according to claim 15, wherein the copper content is in the range of about 3.5 to about 18 percent by weight.

Claim 26 (new): The surface acoustic wave device according to claim 16, wherein the copper content is in the range of about 3.5 to about 25 percent by weight.

Claim 27 (new): The surface acoustic wave device according to claim 16, wherein the electrode pads include aluminum and copper, the copper content being in the range of about 3.5 to about 25 percent by weight.

Claim 28 (new): The surface acoustic wave device according to claim 16, wherein the copper content is in the range of about 3.5 to about 18 percent by weight.